Galaxy Printing Platform

High Accuracy Mass Imaging Platforms

DEK®

Knowhow... Know DEK
...Know the Difference

Galaxy from DEK

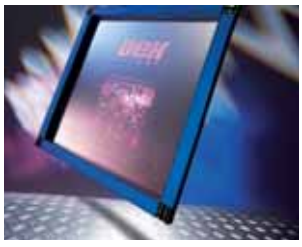
Engineered to deliver new levels of throughput, yield, repeatability and utilization.

Galaxy, from DEK, redefines the upper performance limit for high accuracy mass imaging platforms. Featured for advanced semiconductor packaging applications and high-precision next generation SMT assembly, Galaxy is engineered to deliver new levels of throughput, yield, repeatability and utilization.

The Galaxy platform supports true remote operation, and leverages the DEK Interactiv services portfolio and global support network to operate at the pinnacle for extended periods with only minimal, cost-effective maintenance and adjustments. Because online monitoring and fine-tuning cuts scheduled and unscheduled downtime, site visits, parts costs and scrap. The Instinctiv user interface also delivers a revolutionary operator experience, with task-based layout and controls, TimeToGo real time replenishment status indicators, and on-board error recovery assistance.

The contract-based DEK Interactiv services deliver direct voice help, remote diagnostics, multimedia online tutorials and proactive support including notifications and analysis reports. For further details consult the Interactiv datasheet or contact your DEK representative.

Galaxy embodies new mechanical features including linear motor technology for enhanced speed, accuracy and reliability, and brings forward proven DEK technologies including ProFlow® DirEKt Imaging, as well as advanced optics and lighting for faultless optical inspection at high-throughput. The standard tooling bed accepts all compatible tooling options including Virtual Panel Tooling for arrayed singulated substrates, plus JEDEC wafer chuck and carrier standards for substrate and wafer level processing. Further tooling options include Grid-Lok® or custom tooling for advanced SMT pre-placement in superdense assemblies. SMEMA compatible interfaces support easy integration with DEK wafer loading and substrate fluxing solutions, as well as back-end equipment including grid array reflow or component placement platforms. Standalone, or as part of a turnkey process configured by DEK specialists, Galaxy is the ultimate performer.

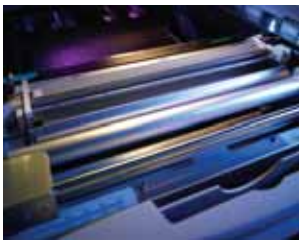


Frameless VectorGuard® Stencil Foil

ProFlow® enclosed print head technology

“Galaxy is engineered to deliver new levels of throughput, yield, repeatability and utilization”

ISO9000-accredited manufacturing sites



Cyclone Understencil Cleaner

“DEK customers can expect more from their equipment and their screen printing partner.”

Enhanced capability

Galaxy delivers flexibility; its immense capability and broad compatibility, combined with rapid changeover create a process-agnostic platform capable of rapid reassignment as business demands dictate. DirEKt Ball Attach to wafers or substrates, at ball diameters down to 0.2mm; wafer bumping by solder paste printing; SMT pre-placement for next generation assemblies including “silicon dust” components: deploy – and redeploy – at will.

This level of convergence delivers the advanced technological capabilities that are essential for emerging packaging technologies and assembly challenges.

- 7 seconds cycle time
- 2.0Cpk repeatability @ ± 12.5µm
- New product set-up in under 10 mins
- High accuracy applications at wafer, substrate and board level
- True remote operation, monitoring and diagnostics operating at the pinnacle for extended periods with only minimal, cost-effective maintenance and adjustment
- Instinctiv™ V9 software enables faster setup and first time print, lower operator training requirements, easier error avoidance and recovery
- Advanced mechanical features including linear motor technology enhance speed, accuracy and reliability
- Standard tooling bed accepts all compatible tooling options including Virtual Panel Tooling for arrayed singulated substrates
- Fast changeover (2 mins) for rapid reassignment as business demands dictate
- ProFlow® DirEKt Imaging technology enables predictable, repeatable ball placement for solder balls as small as 0.2mm for first pass yields above 99.9%
- Advanced optics and lighting for faultless optical inspection at high-throughput
- SMEMA-compatible interfaces support easy integration with DEK wafer loading and substrate fluxing solutions, as well as back-end equipment